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end

preparing said semiconductor package structured by providing a substrate for mounting said semiconductor element thereon to fix said semiconductor element to one side thereof and a connecting pattern provided on the other side of said substrate and by forming a through hole from the one side to the other side of said substrate;

fixing a surface ~~where the element is formed~~ of said semiconductor element ^{to,} on the one side of said substrate of said semiconductor package such that an electrode of said semiconductor element is within said through hole;

electrically connecting said connecting pattern and said electrode of said semiconductor element via wires through said through hole; and

sealing said through hole and said wires with resin.
